

**REMARKS**

Applicant respectfully requests reconsideration of the present application in view of the foregoing amendments and in view of the reasons that follow.

No claims are currently being canceled.

Claims 1, 6, 11 and 18 are currently being amended.

Claims 33-40 are currently being added.

This amendment amends and adds claims in this application. A detailed listing of all claims that are, or were, in the application, irrespective of whether the claims remain under examination in the application, is presented, with an appropriate defined status identifier.

After amending the claims as set forth above, claims 1-4, 6-9, 11-16, 18-23, 25-28 and 33-40 are now pending in this application.

In the Office Action, claims 1-4, 11-16, 25 and 27 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of U.S. Patent No. 6,326,270 to Lee et al. and further in view of U.S. Patent No. 6,333,233 to Kojima; and claims 6-9, 18-23, 26 and 28 were rejected under 35 U.S.C. § 103(a) as being unpatentable over AAPA and Lee et al. in view of Kojima, and further in view of U.S. Patent No. 5,807,779 to Liaw. These rejections, to the extent that they may be applied to the presently pending claims, are traversed for at least the reasons given below.

In Lee et al., since a silicon nitride film 119 is formed directly on a semiconductor substrate 100 as shown in Figure 5 of Lee et al., Lee et al. does not disclose or suggest that a second nitride film is formed on the substrate with any gate oxide film interposed therebetween in a low-density region of the semiconductor substrate 100. Since Lee et al.'s nitride film 119 is formed directly on the semiconductor substrate 100, stress applied to the semiconductor substrate 100 during heat treatment is large, and thus defects

tend to occur on the semiconductor substrate 100. The presently claimed invention prevents such defects from occurring.

Accordingly, since none of the other cited art of record rectifies the above-mentioned deficiencies of Lee et al., presently pending claims 1, 6, 11 and 18 are patentable over the cited art of record.

New claims 33-40 have been added to recite additional features of the present invention that provide a separate basis for patentability of these claims.

Accordingly, since there are no other objections or rejections raised in the Office Action, Applicant believes that the present application is now in condition for allowance, and an early indication of allowance is respectfully requested.

The Examiner is invited to contact the undersigned by telephone if it is felt that a telephone interview would advance the prosecution of the present application.

Lastly, as a procedural matter, the Examiner is requested to acknowledge receipt of the Supplemental Amendment that was filed (based on the Examiner's request telephoned to Applicant's representative) via fax on January 22, 2004.

The Commissioner is hereby authorized to charge any additional fees which may be required regarding this application under 37 C.F.R. §§ 1.16-1.17, or credit any overpayment, to Deposit Account No. 19-0741. Should no proper payment be enclosed herewith, as by a check being in the wrong amount, unsigned, post-dated, otherwise improper or informal or even entirely missing, the Commissioner is authorized to charge the unpaid amount to Deposit Account No. 19-0741. If any extensions of time are needed for timely acceptance of papers submitted herewith, Applicant hereby petitions for such extension under 37 C.F.R. §1.136 and authorizes payment of any such extensions fees to Deposit Account No. 19-0741.

Respectfully submitted,

May 27, 2004  
Date

Phillip J. Articola  
Phillip J. Articola  
Registration No. 38,819

FOLEY & LARDNER LLP

Customer Number: 22428

Telephone: (202) 672-5300

Facsimile: (202) 672-5399